RELIABILITY REPORT
FOR
MAX291CPA+
PLASTIC ENCAPSULATED DEVICES

September 22, 2009

MAXIM INTEGRATED PRODUCTS
120 SAN GABRIEL DR.
SUNNYVALE, CA 94086

Approved by
Ken Wendel
Quality Assurance
Director, Reliability Engineering
Conclusion

The MAX291CPA+ successfully meets the quality and reliability standards required of all Maxim products. In addition, Maxim’s continuous reliability monitoring program ensures that all outgoing product will continue to meet Maxim’s quality and reliability standards.

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I. Device Description

The MAX291/MAX292/MAX295/MAX296 are easy-to-use, 8th-order, lowpass, switched-capacitor filters that can be set up with corner frequencies from 0.1Hz to 25kHz (MAX291/MAX292) or 0.1Hz to 50kHz (MAX295/MAX296). The MAX291/MAX295 Butterworth filters provide maximally flat passband response, and the MAX292/MAX296 Bessel filters provide low overshoot and fast settling. All four filters have fixed responses, so the design task is limited to selecting the clock frequency that controls the filter’s corner frequency. An external capacitor is used to generate a clock using the internal oscillator, or an external clock signal can be used. An uncommitted operational amplifier (noninverting input grounded) is provided for building a continuous time lowpass filter for post-filtering or anti-aliasing. Produced in an 8-pin DIP/SO and a 16-pin wide SO package, and requiring a minimum of external components, the MAX291 series delivers very aggressive performance from a tiny area.
II. Manufacturing Information

A. Description/Function: 8th-Order, Lowpass, Switched-Capacitor Filters
B. Process: S3
C. Number of Device Transistors:
D. Fabrication Location: Oregon
E. Assembly Location: Thailand, Philippines
F. Date of Initial Production: Pre 1997

III. Packaging Information

A. Package Type: 8-pin PDIP
B. Lead Frame: Copper
C. Lead Finish: 100% matte Tin
D. Die Attach: Conductive Epoxy
E. Bondwire: Gold (1.3 mil dia.)
F. Mold Material: Epoxy with silica filler
G. Assembly Diagram: #05-0201-0111
H. Flammability Rating: Class UL94-V0
I. Classification of Moisture Sensitivity per JEDEC standard J-STD-020-C Level 1
J. Single Layer Theta Ja: 110°C/W
K. Single Layer Theta Jc: 40°C/W

IV. Die Information

A. Dimensions: 89 X 95 mils
B. Passivation: Si₃N₄/SiO₂ (Silicon nitride/ Silicon dioxide)
C. Interconnect: Al/0.5%Cu with Ti/TIN Barrier
D. Backside Metallization: None
E. Minimum Metal Width: 3.0 microns (as drawn)
F. Minimum Metal Spacing: 3.0 microns (as drawn)
G. Bondpad Dimensions: 5 mil. Sq.
H. Isolation Dielectric: SiO₂
I. Die Separation Method: Wafer Saw
V. Quality Assurance Information

A. Quality Assurance Contacts:
   Ken Wendel (Director, Reliability Engineering)
   Bryan Preeshl (Managing Director of QA)

B. Outgoing Inspection Level:
   0.1% for all electrical parameters guaranteed by the Datasheet.
   0.1% For all Visual Defects.

C. Observed Outgoing Defect Rate:
   < 50 ppm

D. Sampling Plan:
   Mil-Std-105D

VI. Reliability Evaluation

A. Accelerated Life Test

The results of the 135°C biased (static) life test are shown in Table 1. Using these results, the Failure Rate ($\lambda$) is calculated as follows:

$$\lambda = \frac{1}{\text{MTTF}} = \frac{1.83}{192 \times 4340 \times 80 \times 2}$$

(Chi square value for MTTF upper limit)

(where 4340 = Temperature Acceleration factor assuming an activation energy of 0.8eV)

$$\lambda = 13.4 \times 10^{-9}$$

$$\lambda = 13.4 \text{ F.I.T. (60% confidence level @ 25°C)}$$

The following failure rate represents data collected from Maxim’s reliability monitor program. Maxim performs quarterly life test monitors on its processes. This data is published in the Reliability Report found at http://www.maxim-ic.com/qa/reliability/monitor. Cumulative monitor data for the S3 Process results in a FIT Rate of 0.04 @ 25°C and 0.69 @ 55°C (0.8 eV, 60% UCL)

B. Moisture Resistance Tests

The industry standard 85°C/85%RH or HAST testing is monitored per device process once a quarter.

C. E.S.D. and Latch-Up Testing

The AF11-2 die type has been found to have all pins able to withstand a HBM transient pulse of +/-800 V per Mil-Std 883 Method 3015.7. Latch-Up testing has shown that this device withstands a current of +/-250 mA.
<table>
<thead>
<tr>
<th>TEST ITEM</th>
<th>TEST CONDITION</th>
<th>FAILURE IDENTIFICATION</th>
<th>SAMPLE SIZE</th>
<th>NUMBER OF FAILURES</th>
</tr>
</thead>
<tbody>
<tr>
<td><strong>Static Life Test</strong></td>
<td>Ta = 135°C</td>
<td>DC Parameters &amp; functionality</td>
<td>80</td>
<td>0</td>
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<tr>
<td></td>
<td>Biased</td>
<td></td>
<td></td>
<td></td>
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<tr>
<td></td>
<td>Time = 192 hrs.</td>
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<tr>
<td><strong>Moisture Testing</strong></td>
<td>Ta = 130°C</td>
<td>DC Parameters &amp; functionality</td>
<td>77</td>
<td>0</td>
</tr>
<tr>
<td></td>
<td>RH = 85%</td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td></td>
<td>Biased</td>
<td></td>
<td></td>
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</tr>
<tr>
<td></td>
<td>Time = 96hrs.</td>
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<tr>
<td><strong>Mechanical Stress</strong></td>
<td>Temperature</td>
<td>DC Parameters &amp; functionality</td>
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<td>0</td>
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<tr>
<td></td>
<td>-65°C/150°C</td>
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<tr>
<td></td>
<td>Cycle</td>
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<tr>
<td></td>
<td>1000 Cycles</td>
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<td></td>
<td>Method 1010</td>
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</table>

Note 1: Life Test Data may represent plastic DIP qualification lots.
Note 2: Generic Package/Process data